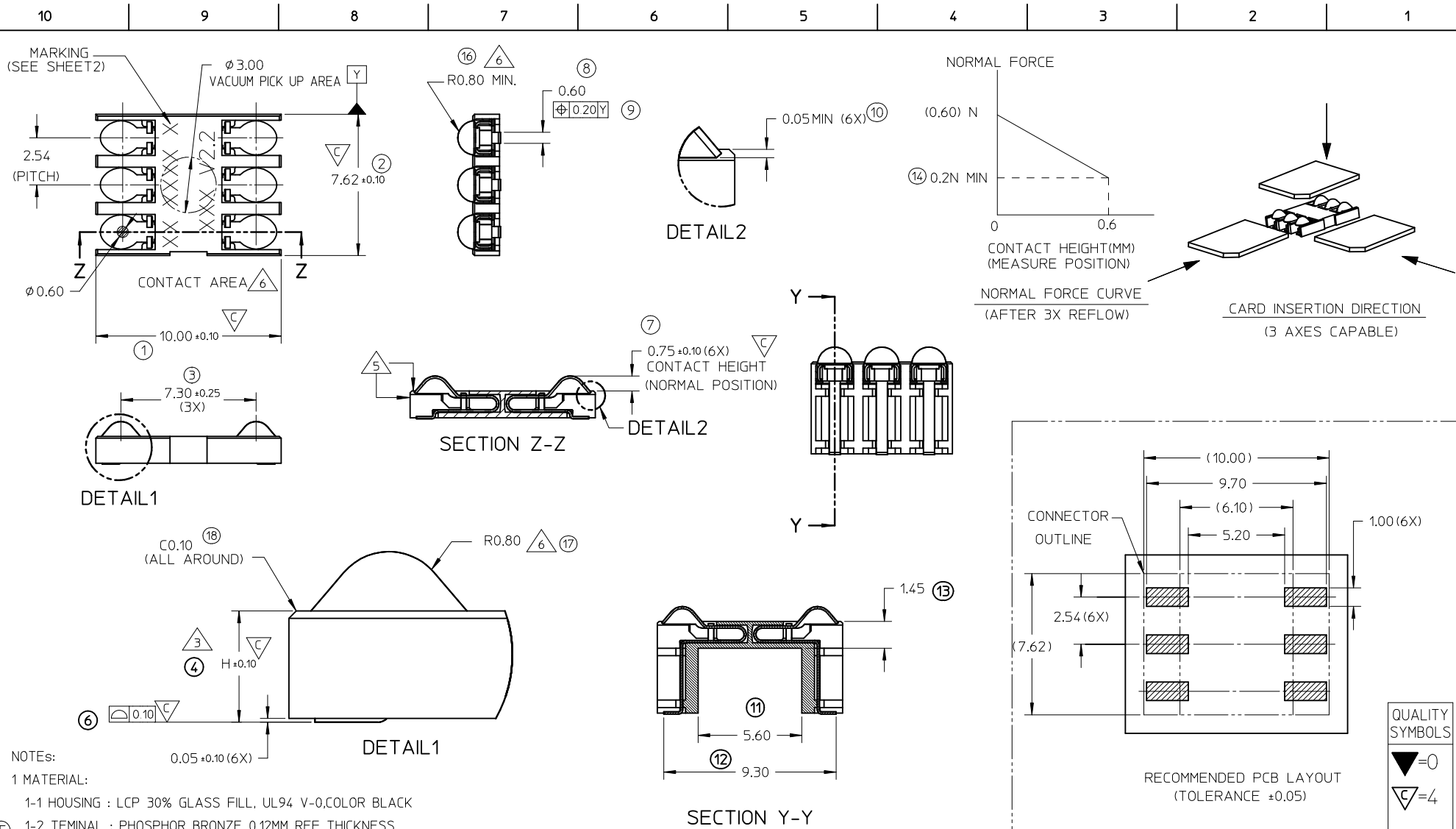




NOTES:

1 MATERIAL:

1-1 HOUSING : LCP 30% GLASS FILL, UL94 V-0,COLOR BLACK

1-2 TERNAL : PHOSPHOR BRONZE 0.12MM REF THICKNESS

2 PLATING:TERMINAL:

2-1 SIM SIDE (CONTACT AREA): 0.8 MICROMETER MIN GOLD

2-1 SOLDER TAIL : GOLD FLASH 0.05 MICROMETER MIN

2-3 UNDERPLATING : 2 MICROMETER NICKEL OVERALL

3 H DIMENSION MINIMUM=1.50,MAXIMUM=5.00(SEE CHART ON SHEET 2)

4 NO SHARP EDGES INTERFACING WITH THE PCB OR SIM CARD

5 CONTACT MUST NOT EXTENDED BEYOND HOUSING EDGE DURING DEFLECTION AND MUST LOWER THAN HOUSING LEVEL AFTER 3 TIMES REFLOW

6 MAINTAIN IN CONTACT AREA

RELEASED EC NO:SH2000-0355 DRWN:JLU39 CHKD:LANDY APPR:WFDENG REV	DESCRIPTION 2010/03/10 2010/03/10 2010/04/02	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION				
				mm	INCH	DRAWN BY JLU	DATE 2004/03/21	TITLE 6 CKT SCALABLE SIM CONNECTOR					
			4 PLACES	± ---	± ---	CHECKED BY Y JWU	DATE 2004/03/21						
			3 PLACES	± ---	± ---	APPROVED BY WFDENG		DATE 2010/03/29	MOLEX INCORPORATED				
			2 PLACES	± 0.10	± ---								
			1 PLACE	± 0.2	± ---	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-47019-001	SHEET NO. 1 OF 2				
			ANGULAR ± 2 °										
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							
						SIZE A3							

